

Title (en)

DEVICE FOR PUNCHING THIN MATERIALS

Title (de)

VORRICHTUNG ZUM STANZEN VON DÜNNWANDIGEN MATERIALIEN

Title (fr)

DISPOSITIF POUR LA DÉCOUPE DE MATERIAUX A ÉPAISSEUR RÉDUITE

Publication

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Application

**EP 16716454 A 20160323**

Priority

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Abstract (en)

[origin: WO2016176784A1] The invention relates to a device, by means of which thin-walled materials, such as labels and flat lids for containers, can be punched in micro or small quantities, comprising a band steel cutting edge (11) that is elastically mounted in the punching direction. The matrix is likewise elastically held on the matrix plate perpendicular to the punching direction by virtue of a matrix receptacle (33) fastened to the region in the matrix plate (27) that is adjacent to the recess (29). On the matrix receptacle, an elastically deformable intermediate plate (47) is placed, and the matrix (55) is placed on the intermediate plate.

IPC 8 full level

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Citation (search report)

See references of WO 2016176784A1

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JP 2018516765 A 20180628; JP 6667553 B2 20200318; KR 102499558 B1 20230213; KR 20180062983 A 20180611; PL 3291952 T3 20191031;  
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